

Forschungsfabrik Mikroelektronik Deutschland

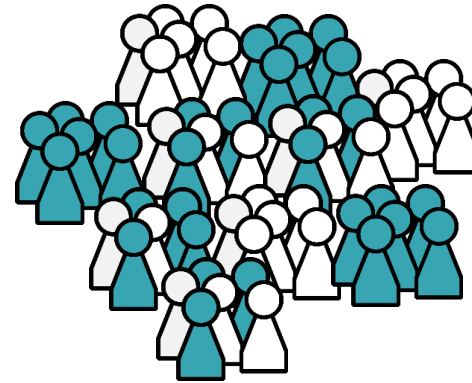
**Fraunhofer Group for Microelectronics in Cooperation with Leibniz
Institutes FBH and IHP**



Solid-State LiDAR : Umgebungssensorik für sicheres autonomes Fahren

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Forschungsfabrik Mikroelektronik Deutschland

FMD Facts – A Short Overview



Within the FMD more than 2.000 scientists work together under a single, virtual roof, **3.500 employees** in total.

Total **investment of 350 Mio. EUR** for additional infrastructure and future developments.

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International Establishment of the FMD and Cooperation with **European Partners** (e.g. NGC Alliance)



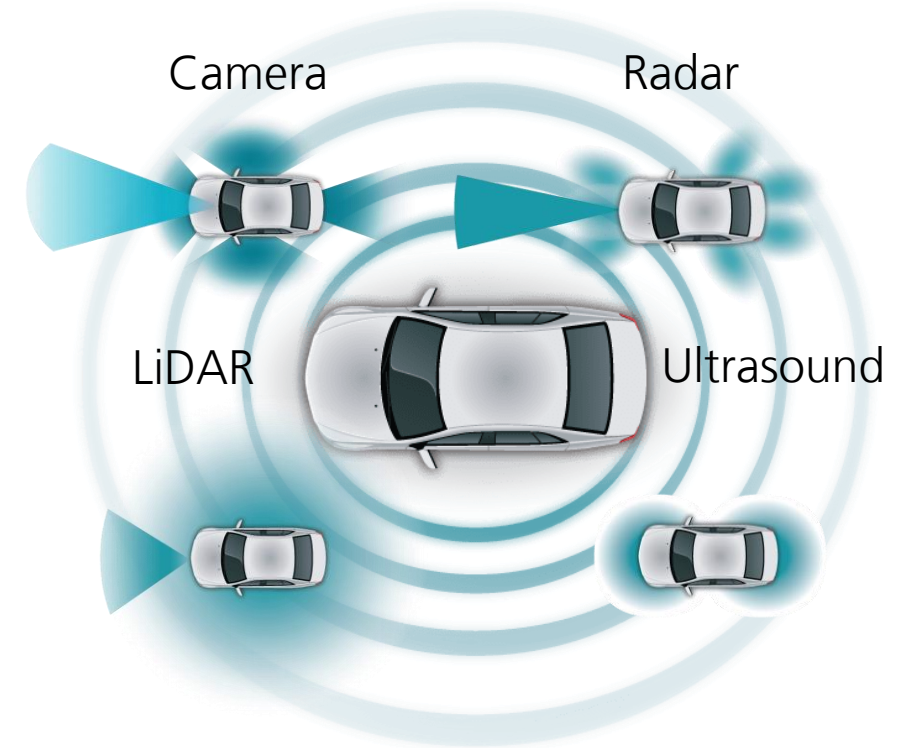
FMD Offer for Customers



<p>Application Specific Solutions</p>	<p>Solid-State LiDAR: Umgebungssensorik für sicheres autonomes Fahren</p>
<p>Technology Platforms</p>	<ul style="list-style-type: none"> ▪ 6 Technology platforms along the value chain ▪ 2 Design platforms
<p>FMD as a strong Fundament</p>	<ul style="list-style-type: none"> ▪ 13 Member institutes of the Fraunhofer-Gesellschaft and Leibniz-Gemeinschaft all over Germany

Vehicle Environmental Recognition

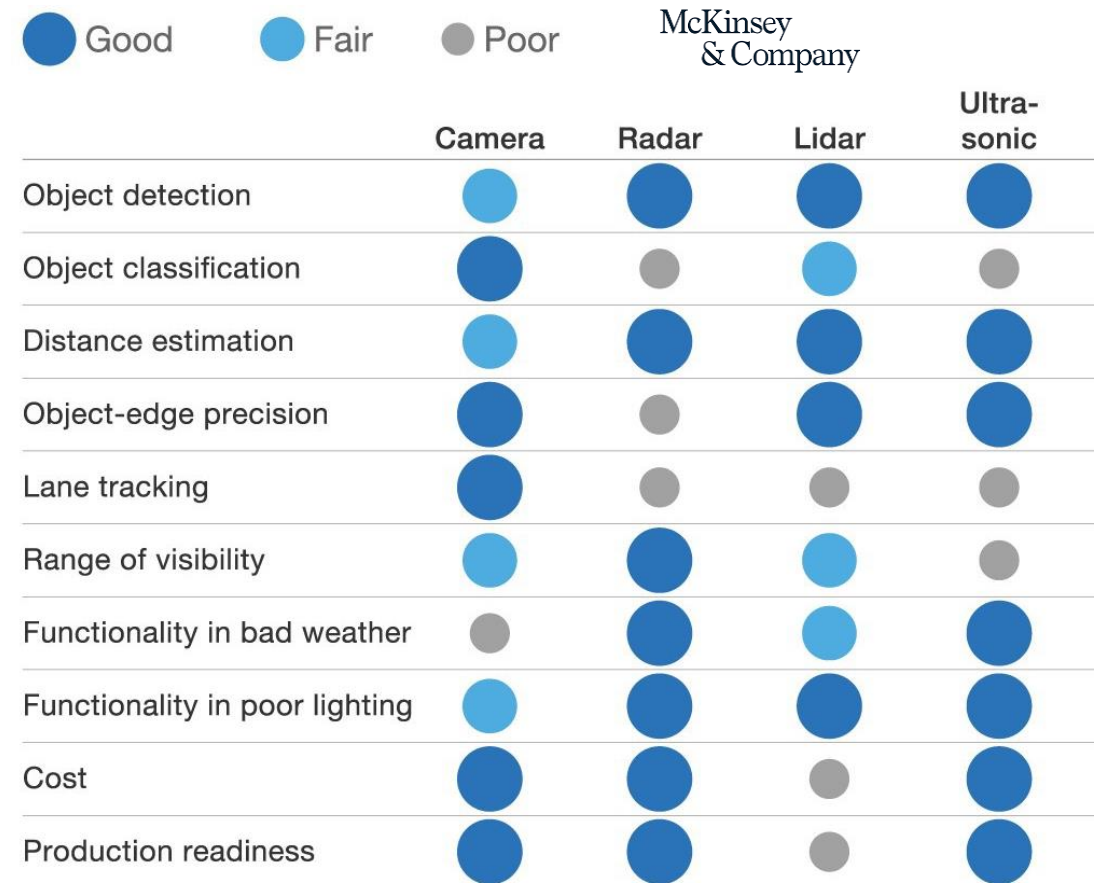
- Safe Vehicle Environmental Recognition is the key technology for autonomous driving
- Solutions & Technologies for Detection
 - Camera
 - LiDAR
 - RADAR
 - Ultrasound



Source: www.ti.com

Vehicle Environmental Recognition

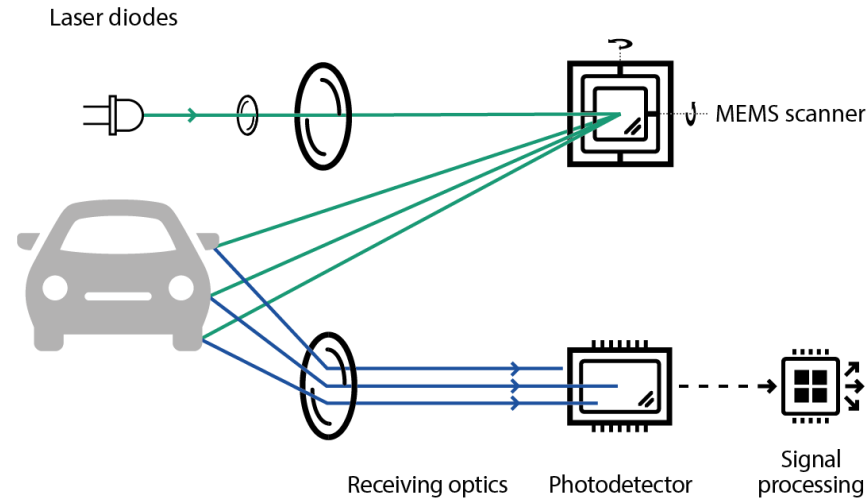
- Only the the combination of at least two different physical detection methods allows safe autonomous driving
- Main challenges for LiDAR are
 - Cost reduction
 - Range
 - Dimension



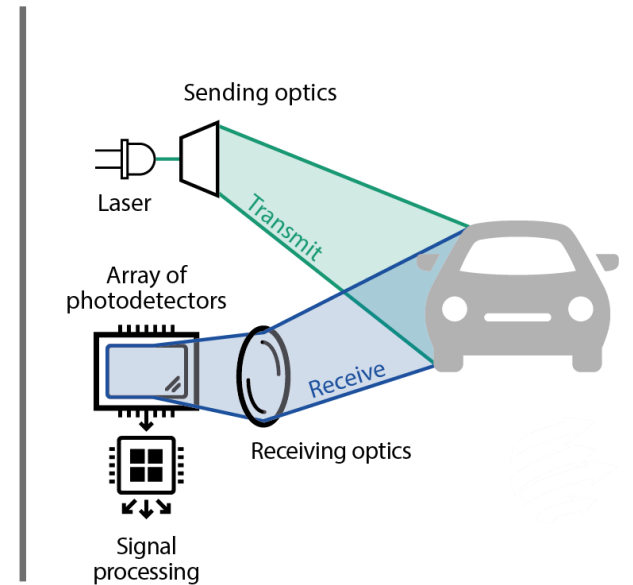
Solid State LiDAR

- Solid State LiDAR systems allows the cost efficient solution for the safe detection in autonomous vehicles

- LiDAR system approaches
 - MEMS-based scanning LiDAR
 - Flash LiDAR
 - OPA
- Optical Wavelengths
 - 905nm as well as 1550nm



MEMS based scanning LiDAR



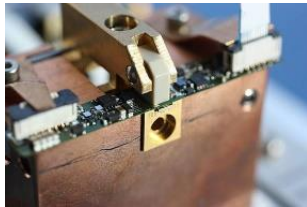
Flash LiDAR

LiDAR - Elements along the entire value chain

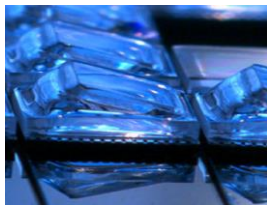
Laser Sources Sending Optics Beam Steering Receiving optics Detectors Signal processing / Sensor data fusion

905 nm

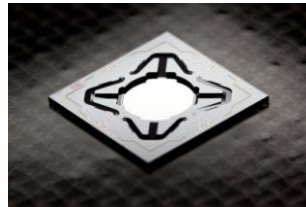
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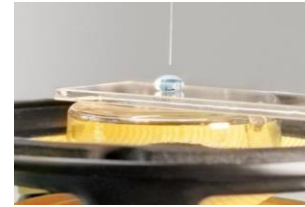


IPMS



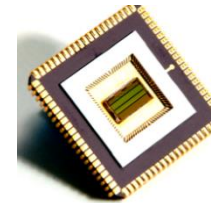
Receiving optics

IOF



Detectors

IMS



Signal processing / Sensor data fusion

FHR



1550 nm

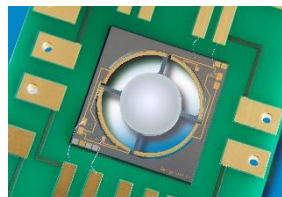
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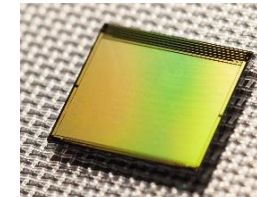
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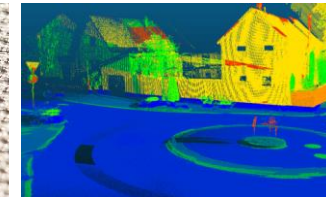
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IAF



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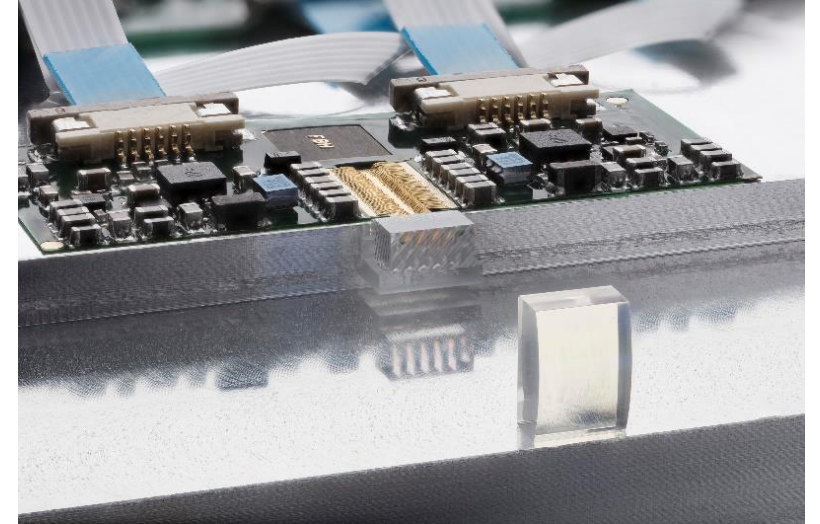


Design and Test (IIS), Advanced System Integration (IZM)

LiDAR - Components

Laser sources

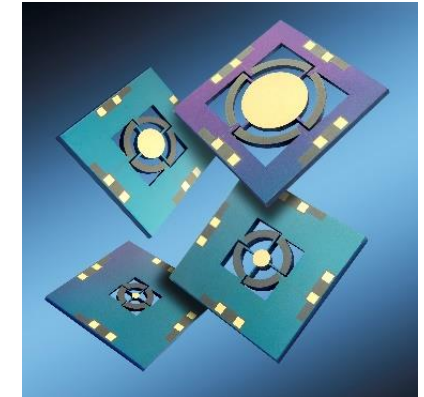
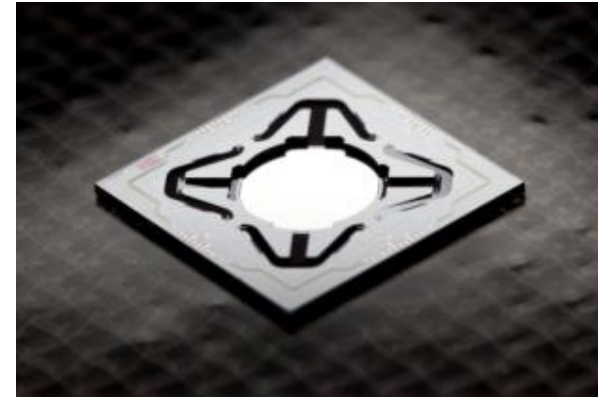
- **905 nm: GaAs-based diode lasers**
 - Distributed Bragg reflector (DBR) broad area (BA) laser
 - Optical pulse lengths 3 ... 10 ns
 - Emission wavelength 904 nm @ $T = 25^{\circ}\text{C}$
 - Wavelength shift < 10 nm between temperatures of -40°C and $+85^{\circ}\text{C}$
 - Pulse power 100 W @ 85°C (3-emitter chip)
 - Spot of combined beam 90 cm x 56 cm at distance of 180 m
- **1500 nm: InP diode lasers at 1500 nm**
 - BA-lasers: cw operation: 5 W; pulsed operation: 16 W (300 ns)
 - Coherent light source and tunable lasers for beam steering for FMCW LiDAR
 - Higher eye safety power limit



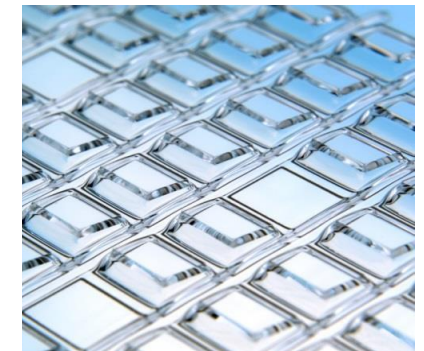
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LiDAR - Components MEMS Scanners

- 1D and 2D scanning devices (arrays possible)
- Resonant and quasistatic deflections
- Drive mechanisms are designed application-specific:
 - Electrostatic
 - Piezoelectric
 - Magnetic
- Scan ranges from 0.1° up to 180°
- Mirror diameters: 0.5 mm - 50 mm
- Scan frequency: 0.1 Hz - 100 kHz
- Fatigue free, high temperature resistant, highly reflective coatings (R>99%)



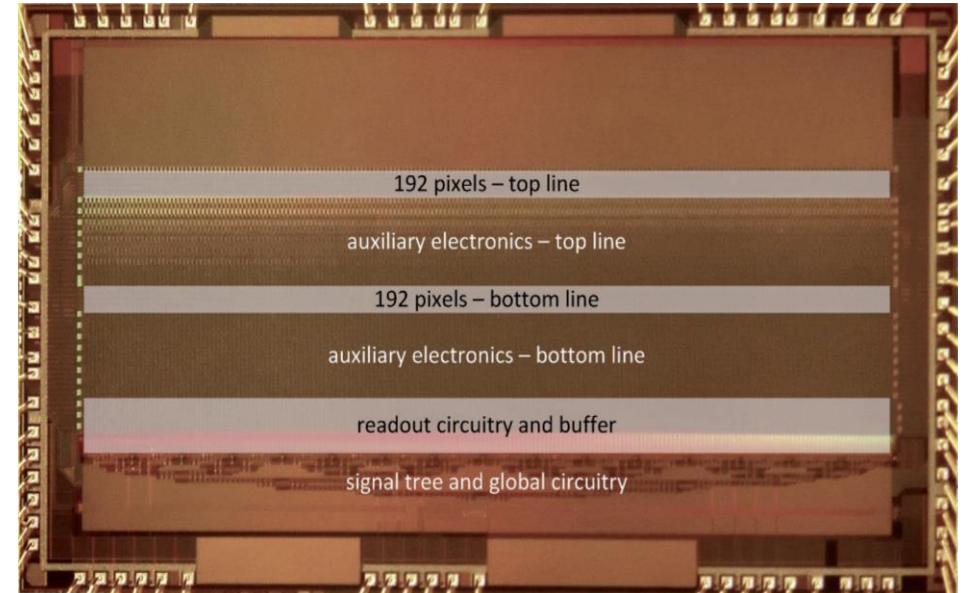
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LiDAR - Components

Silicon detecotors

- **Single Photon Avalanche Diode (SPAD)**
- **arrays at 905 nm**
 - Avalanche photodiode operated in Geiger-Mode
 - High spatial resolution and on-chip signal processing (AI on chip)
 - No analog signal processing needed
 - Compatible to CMOS process technology
 - High volume production at low cost
 - Background light suppression



SPADeye2 Sensor, 192x2 Pixel, 9 x 5.2 mm²

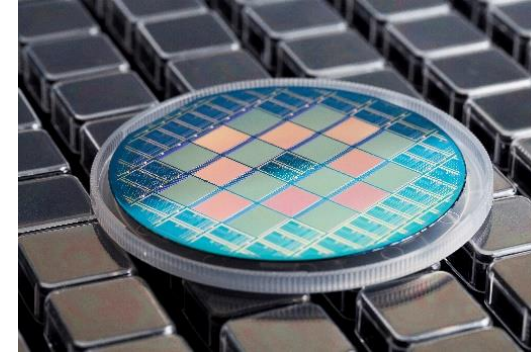
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LiDAR - Components

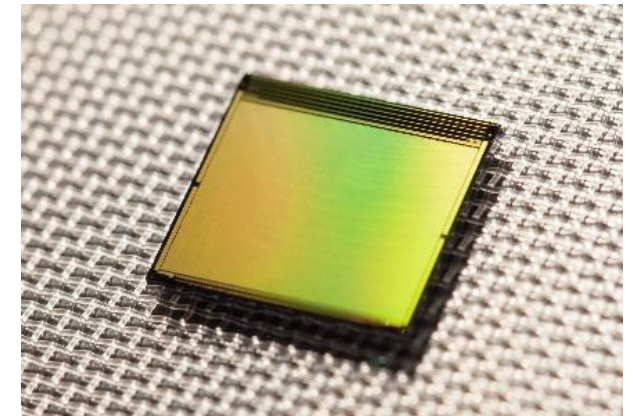
III/V Semiconductor Detectors

▪ InGaAs-based APDs (SWIR) at 1550 nm

- High-resolution InGaAs APD focal plane arrays with 640 x 512 pixels
- Spectral sensitivity up to 1650 nm
- Operation in proportional mode
- Internal signal amplification (gain)
- Design of coherent photodetectors, needed for FMCW or phase shift LiDAR systems
- Monolithic integration of SWIR detectors and the corresponding laser source can be realized
- Laser gated viewing systems (Flash LiDAR)
 - Maximum Range > 1 km
 - Distance resolution < 1 m
 - Lateral resolution > VGA

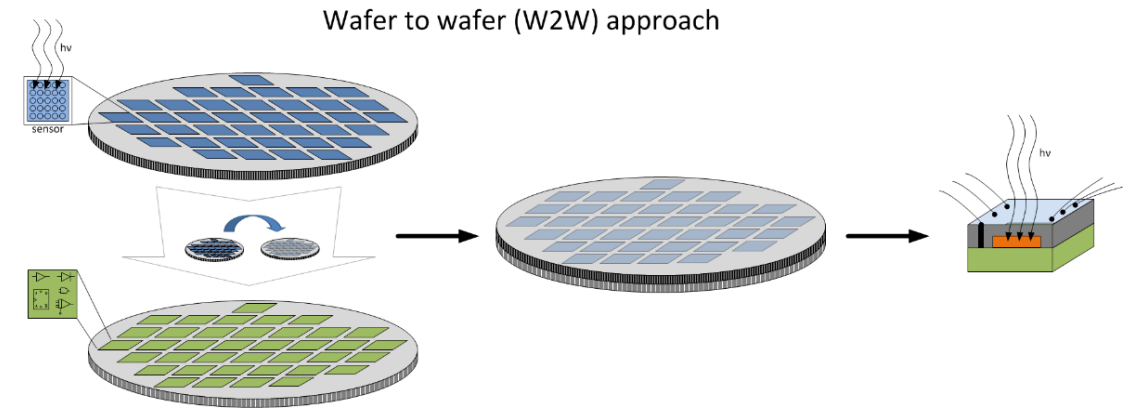


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LiDAR - Systems Integration Technologies

- 3D integration technologies for LiDAR
 - 3D IC Technology with TSV and RDL
 - Wafer Level Packaging & Assembly
- SPAD on CMOS integration
 - 3D-SPAD with 40 μm pitch
 - Wafer processing with TSVs, RDL, bumping and flip chip assembly of thin SPADs
- SiPM integration
 - Edgeless design with high voltage isolation
- Optical and thermal design, simulation and measurement techniques
- Wafer Level Optics Integration
 - Vacuum packaging by hermetic encapsulation with inclined glass caps



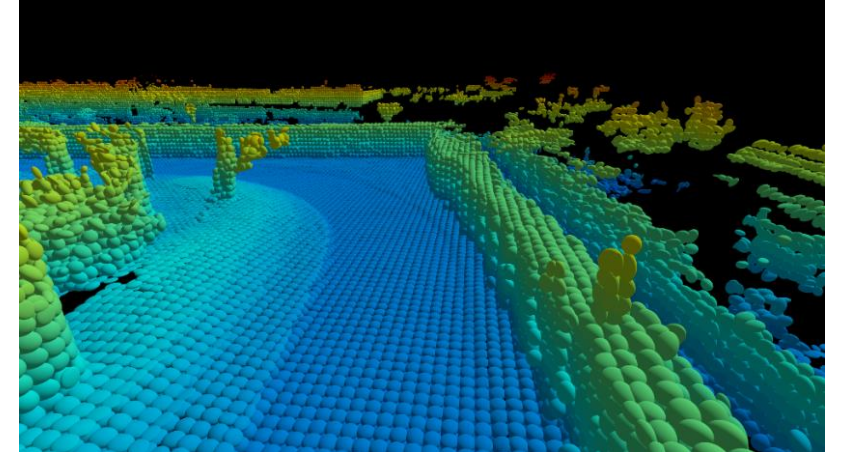
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LiDAR - Systems

Sensor Data Fusion

- Multi-Sensor Fusion (LiDAR, RADAR, Camera,...)
- Environment perception for autonomous vehicles
- Sensor Cloud (BDC Web)
 - Storage and management of position- and time-synchronous data
 - Automated algorithms for data analysis and data elevation
- FLLT Labeling Toolchain:
 - Automated labeling of point clouds and training data for AI
 - The larger the data pool, the better the computer system can learn → automated labeling
 - Web-based solution for the labeling process (data overview, data review, data labeling)



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Conclusion

- The safe, cost effective and robust environmental detection is the key parameter for autonomous driving
- Solid State LiDAR systems are important for the safe optical detection of the surrounding
- The FMD offers all parts of solid-state LiDAR solutions along the whole value chain for the autonomous driving of the future

DANKE

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